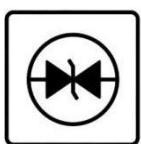




ESD



TVS



TSS



MOV



GDT



PLED

## RCLAMP0531T.TCT-MS

Product specification

## Features

- 80Watts peak pulse power ( $t_p = 8/20\mu s$ )
- Tiny SLP1006-2 package
- Bidirectional configurations
- Solid-state silicon-avalanche technology
- Low clamping voltage
- Low leakage current
- Low capacitance ( $C_j=0.5\text{pF}$  typ. IO to IO)
- Protection one data/power line to:
- IEC 61000-4-2  $\pm 15\text{kV}$  contact  $\pm 8\text{kV}$  air
- IEC 61000-4-4 (EFT) 40A (5/50ns)
- IEC 61000-4-5 (Lightning) 4A (8/20 $\mu s$ )

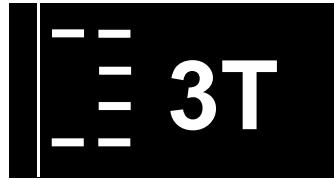
## Mechanical Data

- SLP1006-2 package
- Molding compound flammability rating: UL 94V-0
- Packaging: Tape and Reel
- RoHS/WEEE Compliant

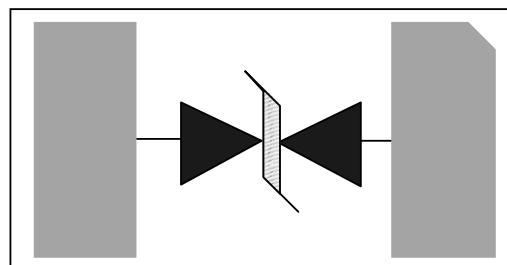
## Applications

- Cell Phone Handsets and Accessories
- Microprocessor based equipment
- Personal Digital Assistants (PDA's)
- Notebooks, Desktops, and Servers
- Portable Instrumentation

## Reference News

SLP1006P2T	Marking
	

## Schematic & PIN Configuration



**Absolute Maximum Rating**

Rating	Symbol	Value	Units
Peak Pulse Power ( $t_p = 8/20\mu s$ )	$P_{PP}$	80	Watts
Peak Pulse Current ( $t_p = 8/20\mu s$ ) (note1)	$I_{pp}$	4.0	A
ESD per IEC 61000-4-2 (Air) ESD per IEC 61000-4-2 (Contact)	$V_{ESD}$	20 20	kV
Lead Soldering Temperature	$T_L$	260(10seconds)	°C
Junction Temperature	$T_J$	-55 to + 125	°C
Storage Temperature	$T_{stg}$	-55 to + 125	°C

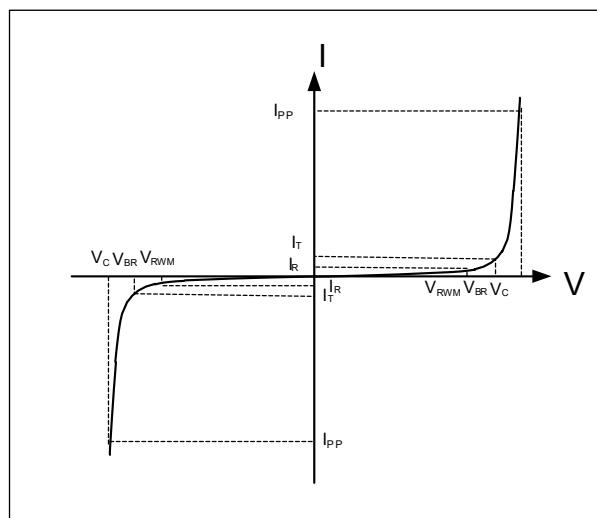
**Electrical Characteristics**

Parameter	Symbol	Conditions	Min	Typical	Max	Units
Reverse Stand-Off Voltage	$V_{RWM}$				5.0	V
Reverse Breakdown Voltage	$V_{BR}$	$I_T = 1\text{mA}$	6.0			V
Reverse Leakage Current	$I_R$	$V_{RWM} = 5\text{V}, T = 25\text{ °C}$			100	nA
Peak Pulse Current	$I_{PP}$	$t_p = 8/20\mu s$			4.0	A
Clamping Voltage	$V_C$	$I_{PP} = 4\text{A}, t_p = 8/20\mu s$			24	V
Junction Capacitance	$C_j$	$I_0 \text{ to } I_0$ $V_R = 0\text{V}, f = 1\text{MHz}$		0.5	0.8	pF

**Electrical Parameters (TA = 25°C unless otherwise noted)**

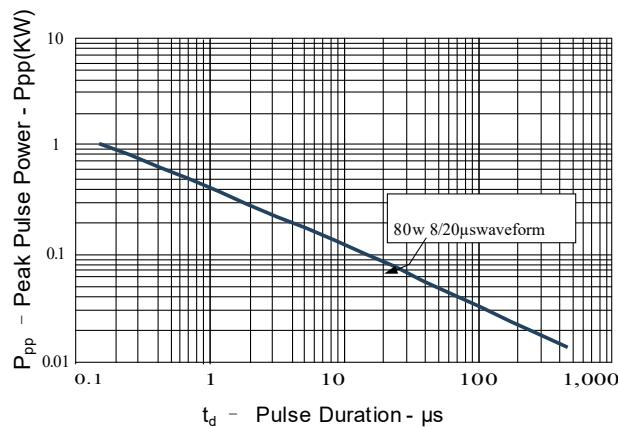
Symbol	Parameter
$I_{PP}$	Maximum Reverse Peak Pulse Current
$V_C$	Clamping Voltage @ $I_{PP}$
$V_{RWM}$	Working Peak Reverse Voltage
$I_R$	Maximum Reverse Leakage Current @ $V_{RWM}$
$V_{BR}$	Breakdown Voltage @ $I_T$
$I_T$	Test Current

Note: 8/20μs pulse waveform.

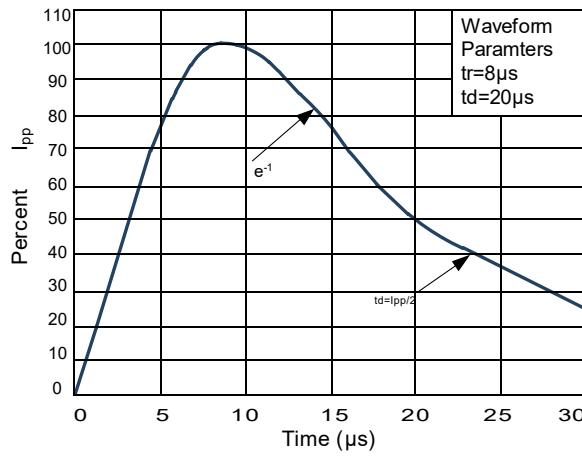


## Typical Characteristics

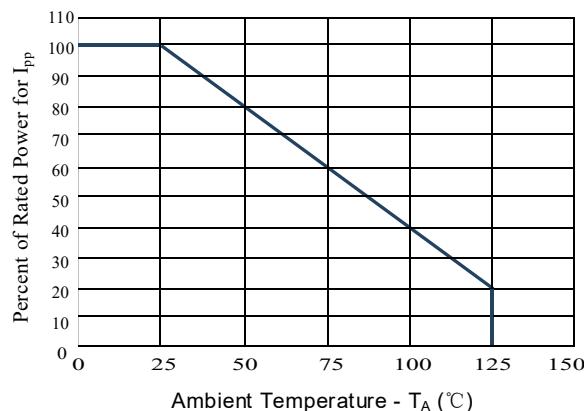
**Figure 1: Peak Pulse Power vs. Pulse Time**



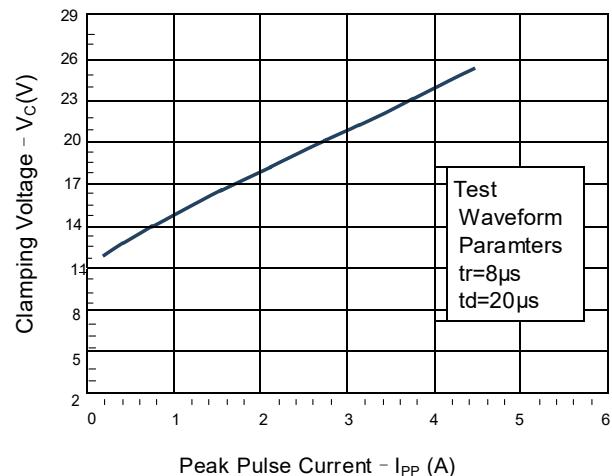
**Figure 3: Pulse Waveform**

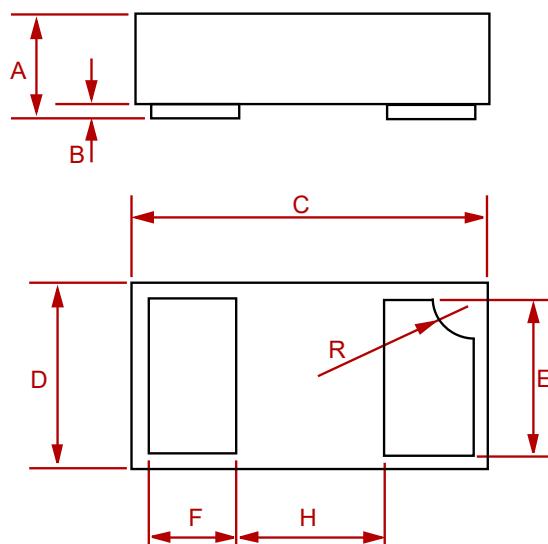


**Figure 2: Power Derating Curve**

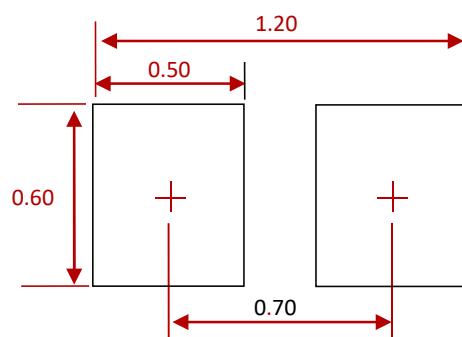


**Figure 4: Clamping Voltage vs. Ipp**



**PACKAGE MECHANICAL DATA**


Dim	Inches		Millimeters	
	MIN	MAX	MIN	MAX
A	0.0125	0.02	0.32	0.52
B	0.000	0.002	0.00	0.05
C	0.037	0.043	0.95	1.080
D	0.022	0.027	0.55	0.680
E	0.016	0.024	0.40	0.60
F	0.008	0.012	0.20	0.30
H	0.015Typ.		0.40Typ.	
R	0.001	0.005	0.05	0.15

**Suggested Pad Layout**

**NOTES:**

1. CONTROLLING DIMENSIONS ARE IN MILLIMETERS (ANGLES IN DEGREES).
2. THIS LAND PATTERN IS FOR REFERENCE PURPOSES ONLY.  
CONSULT YOUR MANUFACTURING GROUP TO ENSURE YOUR COMPANY'S MANUFACTURING GUIDELINES ARE MET.

**Order information**

Orderable Device	Package	Packing Option
RCLAMP0531T.TCT-MS	SLP1006-2	3000PCS

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